

MicroSystem Based on SiP Technology

This book is a comprehensive SiP design guide book. It is divided into three parts: concept and technology, design and simulation, project and case, for a total of 30 chapters.

In Part one, the author proposes some new original concepts and thoughts, such as Function Density Law, Si³P and 4D integration. Part one also covers the latest technology of SiP and Advanced Packaging.

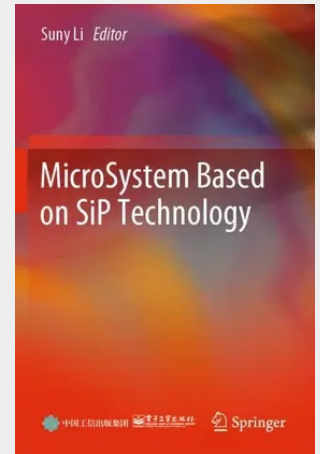
Part two covers the latest SiP and Advanced Packaging design and simulation technologies, such as wire bonding, multi-step cavity, chip stacking, 2.5D TSV, 3D TSV, RDL, Fan-In, Fan-Out, Flip Chip, Embedded Passive, Embedded Chip, RF design, Rigid-Flex design, 4D SiP design, Multi-layout project and Team design, as well as SI, PI, thermal simulation, electrical verification and physical verification.

Based on a real design case, part three introduces the design, simulation and implementation methods of different types of SiP, which has a -important reference significance for the research and development of SiP projects.

This book comprehensively and deeply expounds the latest development, design ideas and design methods of contemporary SiP technology from three aspects: concept and technology, design and simulation, project and case.

Through the detailed introduction of new concepts, design methods, actual projects and cases, this book describes the whole process of SiP products from the beginning of conception to the final realization and makes readers benefit from it.

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